

AMENDMENTS - Version with Markings to Show Changes Made

In the Claims

Please cancel claims 1-13, 18 and 22.

Please amend claims 14-17 and 19-21, and add new claims 23-30 as follows:

14. (Amended) An electronic device comprising;  
a substrate[,]  
having first and second generally planar surfaces, wherein the first generally planar surface is parallel to the second generally planar surface;

one or more electronic parts [that are] mounted on the [main] first generally planar surface; [ of said substrate,]  
a resin [part] layer disposed to [that is formed on the main surface of said substrate so that said resin part fills a specified space] surround[ing] at least one of the one or more [said] electronic parts; [,] and

a plurality of terminal electrodes disposed only on the second generally planar surface and electrically coupled to the one or more electronic parts [that are exposed to the outside].

15. (Amended) The electronic device of Claim 14,  
further comprising [with] an intermediate layer comprising [consisting of] an insulating elastic material interposed between the resin layer and the first generally planar surface [formed on the main surface of said substrate so that said intermediate layer fills a specified space surrounding said electronic parts].

16. (Amended) The electronic device of Claim 14 or Claim 15, [with said]wherein the substrate [having the shape of] comprises a rectangular solid of a specified thickness.

17. (Amended) The electronic device of Claim 14 or Claim 15, [with said]wherein the resin [part] layer comprises [having the shape of] a rectangular solid [that is formed to] of a specified thickness, the resin layer disposed over the [entire main] first generally planar surface [of said substrate, and the side surfaces of said resin part are positioned in the same planes as the side surfaces of said substrate].

19. (Amended) The electronic device of Claim 14 or Claim 15, wherein the [with said] resin layer comprises [part consisting of a resin in which at least one of] a ferrite filler or a metal filler[ is dispersed].

20. (Amended) The electronic device of Claim 14 or Claim 15, wherein the [with said] resin layer comprises at least one of the following properties: [part consisting of a resin which has at least one of] insulation[ng properties], heat resistance, fluid impermeability[waterproof] or chemical resistance.

21. (Amended) The electronic device of Claim 14 or Claim 15, wherein the electronic device comprises [with said] at least one layer selected [of] from the group consisting of: an electromagnetic field shielding layer, a heat-dissipating

layer or a metal layer[ formed in a specified region on the surface of said resin part],

wherein the at least one layer is disposed on at least a specified region of the resin layer.

23. (New) An electronic device comprising;  
a substrate having first and second generally planar surfaces;

one or more electronic parts mounted on the first generally planar surface;

a resin layer disposed to surround at least one of the one or more electronic parts;

an intermediate layer comprising an insulating elastic material interposed between the resin layer and the first generally planar surface; and

a plurality of terminal electrodes electrically coupled to the one or more electronic parts.

24. (New) The electronic device of Claim 23, wherein the substrate comprises a rectangular solid of a specified thickness.

25. (New) The electronic device of Claim 23, wherein the resin layer comprises a rectangular solid of a specified thickness, the resin layer disposed over the first generally planar surface.

26. (New) The electronic device of Claim 23, wherein the resin layer comprises a plurality of resin side surfaces orthogonal to the first generally planar surface, the plurality

of terminal electrodes embedded in the resin layer so that each of the plurality of terminal electrodes are disposed flush with one of the plurality of resin side surfaces.

27. (New) The electronic device of Claim 23, wherein the substrate further comprises a plurality of substrate side surfaces orthogonal to the first generally planar surface, wherein the plurality of terminal electrodes are embedded in the substrate so that each of the plurality of terminal electrodes are disposed flush with one of the plurality of substrate side surfaces.

28. (New) The electronic device of Claim 23, wherein the resin layer comprises a ferrite filler or a metal filler.

29. (New) The electronic device of Claim 23, wherein the resin layer comprises at least one of the following properties: insulation, heat resistance, fluid impermeability or chemical resistance.

30. (New) The electronic device of Claim 23, wherein the electronic device comprises at least one layer selected from the group consisting of: an electromagnetic field shielding layer, a heat-dissipating layer or a metal layer wherein the at least one layer is disposed on at least a specified region of the resin layer.